Initial Product/Process Change Notification

Document #:IPCN25729X
Issue Date:26 Feb 2024

Title of Change:	Wafer Fab Site Addition of onsemi, Bucheon Korea as alternate fab site for ESD and Surge Protection products
Proposed First Ship date:	05 Jul 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or norhayati.othman@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Bucheon, Korea	LA Semiconductor, Idaho, United States

Description and Purpose:

onsemi wants to notify its customers regarding the qualification of onsemi, Bucheon Korea as additional wafer fab for ESD and Surge Protection products.

	Before Change Description	**After Change Description**
Manufacturing locations for Wafer Fab	LA Semiconductor, Idaho, United States	onsemi Bucheon, Korea

There are no product marking changes as a result of this change.

Qualification Plan:

QV DEVICE NAME: ESDL2012MX4T5G
RMS: S93678
PACKAGE: X4DFN

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C	
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	1550 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

QV DEVICE NAME: ESD7321MUT5G
RMS: S94408
PACKAGE: X3DFN

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C	
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Estimated date for qualification completion: 23 February 2024

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal*****.**

Part Number	Qualification Vehicle
ESDL2012MX4T5G	ESDL2012MX4T5G
ESD7321MUT5G	ESD7321MUT5G
ESD8472MUT3G	ESD7321MUT5G
ESD8472MUT5G	ESD7321MUT5G
ESD8472BMUT5G	ESD7321MUT5G